2.0x1.25mm SMD CHIP LED LAMP

Part Number: KPHCM-2012SYCK

Super Bright Yellow

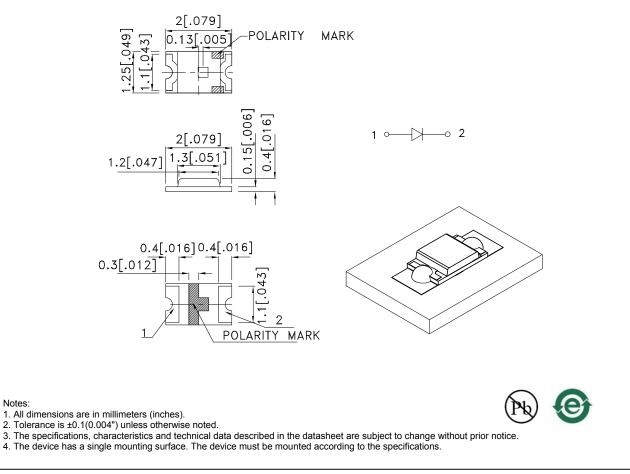
Features

- 2.0X1.25mm SMT LED,0.5mm max. thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

Package Dimensions



SPEC NO: DSAE6001 APPROVED: WYNEC REV NO: V.8 CHECKED: Allen Liu DATE: DEC/20/2010 DRAWN: Y.H.Wu PAGE: 1 OF 5 ERP: 1203003837

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]	
			Min.	Тур.	201/2	
KPHCM-2012SYCK	Super Bright Yellow (AlGaInP)	Water Clear	80	150	110°	

Notes: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

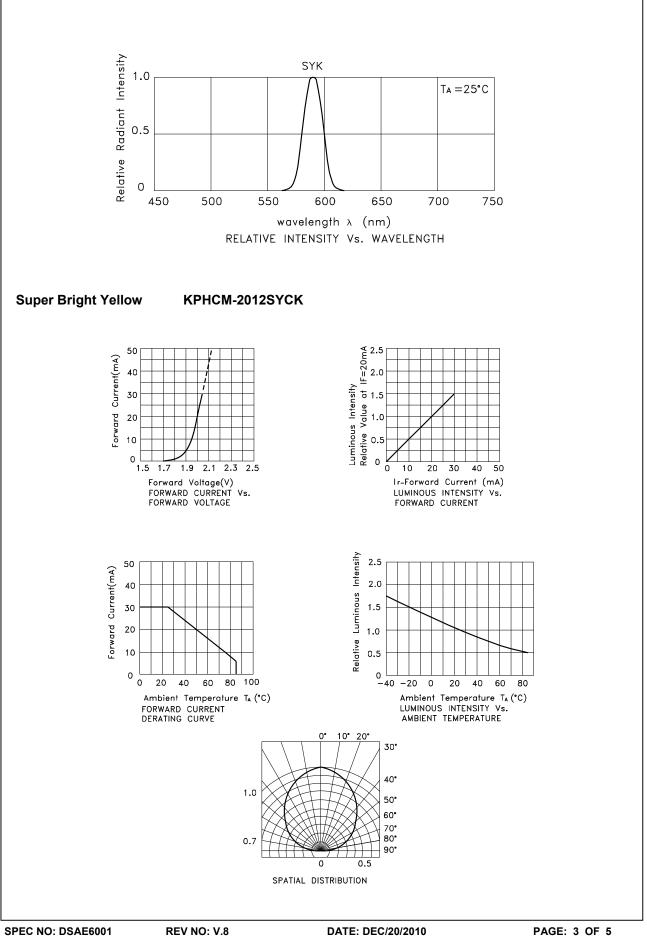
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Yellow	590		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20		nm	IF=20mA
С	Capacitance	Super Bright Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Yellow	2	2.5	V	I⊧=20mA
IR	Reverse Current	Super Bright Yellow		10	uA	VR=5V

Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Yellow	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	175	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

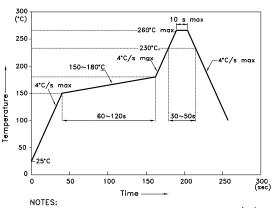
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



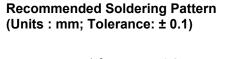
KPHCM-2012SYCK

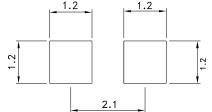
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

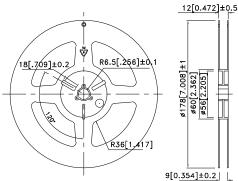


NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

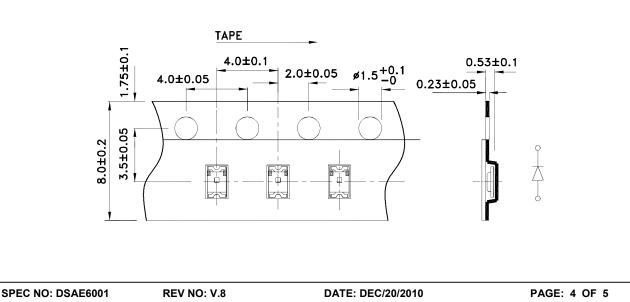




Reel Dimension



Tape Dimensions (Units : mm)



CHECKED: Allen Liu

DRAWN: Y.H.Wu

ERP: 1203003837

